

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-15. (Canceled)

16. (Currently amended) A semiconductor device comprising:

an island on which a first ~~semiconductor~~ circuit element, comprising a semiconductor element, is mounted affixed;

a plurality of first leads which extend around the island and are electrically connected to the first ~~semiconductor~~ circuit element;

a sealing resin which seals the first ~~semiconductor~~ circuit element, the island, and the first leads; ~~and~~

a cavity ~~portion provided~~ in the sealing resin, wherein a second ~~semiconductor~~ circuit element is stored in the cavity; ~~and~~ ~~portion~~

second leads, wherein one end thereof is electrically connected to the second circuit element inside the cavity and the other end thereof is exposed from the sealing resin,

wherein a position of each second lead exposed inside the cavity corresponds to a position of an electrode on a rear surface of the second circuit element; and wherein the first circuit element is located in an area other than the cavity.

17-18. (Canceled)

19. (Currently amended) The device of claim 16 wherein the first ~~semiconductor~~ circuit element is adapted to perform signal processing, and the second ~~semiconductor~~ circuit element includes a memory portion controlled by the first ~~semiconductor~~ circuit element.

20. (Currently amended) A method for manufacturing a semiconductor device comprising :

sealing a first ~~semiconductor~~ circuit element, comprising a semiconductor element electrically connected to first leads, ~~an external electrode~~ with a sealing resin;

providing a cavity ~~portion~~ in the sealing resin; and

storing a second ~~semiconductor~~ circuit element in the cavity, ~~portion~~ wherein the first leads extend around an island on which the first circuit element is disposed and are electrically connected to the first circuit element, and wherein second leads include one end electrically connected to the second circuit element inside the cavity and another end exposed from the sealing resin;

wherein a position of each second lead exposed inside the cavity corresponds to a position of an electrode on a rear surface of the second circuit element, and the first circuit element is located in an area other than the cavity.

21. (Currently amended) The method of claim 20 wherein the second ~~semiconductor~~ circuit element is stored in the cavity portion after performing a test of the first ~~semiconductor~~ circuit element.

22. (Currently amended) The method of claim 20 including:

placing the second ~~semiconductor~~ circuit element on ~~connection terminals~~ the second leads provided in the cavity ~~portion~~, and

fixedly fitting the second ~~semiconductor~~ circuit element ~~as part of mounting the semiconductor device~~ by a reflow process.

23. (New) The device of claim 16 comprising:

third leads, wherein one end thereof is close to the island and the other end thereof is exposed to the cavity, wherein the first circuit element is electrically connected to the second circuit element through the third leads.